Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method of manufacturing an electro-optical device, the method comprising:

forming a plurality of chips each of which includes a drive circuit on a first substrate, a plurality of first connection terminals being formed on a same face of each of the plurality of chips;

forming wires for connecting one of the plurality of chips with a plurality of pixel electrodes, wherein the plurality of pixel electrodes are formed on a second substrate; and

transferring at least one of the plurality of chips from the first substrate onto the second substrate.

2. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 1, further comprising forming a plurality of pixel electrodes on the second substrate after the forming wires.

3. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 2, further comprising forming a plurality of electro-optical elements on the second substrate after the forming of the plurality of pixel electrodes.

4. (Canceled)

5. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 1, the plurality of first connection terminals being arranged in a deposition of two lines.

6. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 1, the wires including a plurality of second connection terminals connected with pixel electrodes.

7. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 6, the transferring at least one of the plurality of chips including fixation of the plurality of chips by connecting each of the plurality of the first connection terminals with at least one of the plurality of the second connection terminals.

8. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 7, the transferring at least one of the chips including forming an adhesive layer on the first connection terminals or the second connection terminals.

9-14. (Canceled)

15. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 1, the forming of the plurality of chips including forming a peeling layer between the plurality of chips and the second substrate.

16. (Previously Presented) The method of manufacturing an elector-optical device according to Claim 15, the peeling layer being formed of a material having a bond that is weakened by application of an energy.

17. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 1, the drive circuit controlling a plurality of electro-optical elements.

18. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 17, the drive circuit including a first transistor for controlling current flowing in the at least one of the plurality of electro-optical elements and a second transistor for operating the first transistor in accordance with input signals.

19. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 17, the drive circuit including a plurality of first transistors for each of

which controls current flowing in the at least one of the plurality of electro-optical elements and a plurality of second transistors whose gates are connected by a common line.

20-21. (Canceled)

22. (Previously Presented) The method of manufacturing an electro-optical device according to Claim 1, the drive circuit to drive a plurality of pixels individually.

23. (New) The method of manufacturing an electro-optical device according to Claim 1, the first substrate being formed of a material having a light transmitting property.